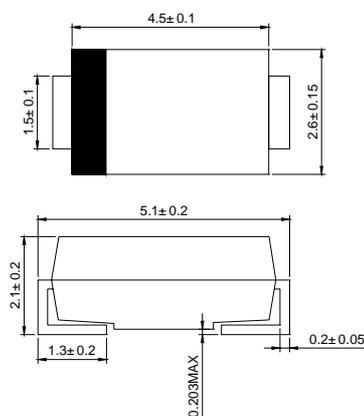


FEATURES

- ◇ Low cost
- ◇ Low leakage
- ◇ Low forward voltage drop
- ◇ High current capability
- ◇ Easily cleaned with Alcohol, Isopropanol and similar solvents
- ◇ The plastic material carries U/L recognition 94V-0

MECHANICAL DATA

- ◇ Case: JEDEC DO-214AC, molded plastic
- ◇ Terminals: Solderable per MIL- STD-202, Method 208
- ◇ Polarity: Color band denotes cathode
- ◇ Weight: 0.003 ounces, 0.093 grams
- ◇ Mounting position: Any

DO-214AC(SMA)


Dimensions in millimeters

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate by 20%.

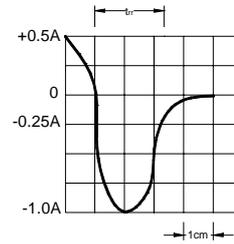
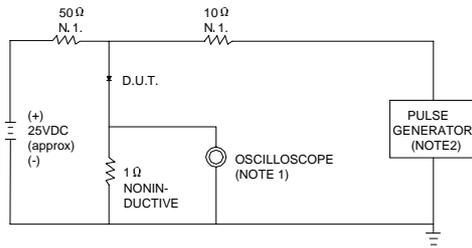
		ES2A	ES2B	ES2C	ES2D	ES2G	ES2H	ES2J	NITS	
Maximum recurrent peak reverse voltage	V_{RRM}	50	100	150	200	400	500	600	V	
Maximum RMS voltage	V_{RMS}	35	70	105	140	280	350	420	V	
Maximum DC blocking voltage	V_{DC}	50	100	150	200	400	500	600	V	
Maximum average forward rectified current @ $T_A=110^\circ\text{C}$	$I_{F(AV)}$	2.0							A	
Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load @ $T_J=125^\circ\text{C}$	I_{FSM}	50							A	
Maximum instantaneous forward voltage at 2.0 A	V_F	0.98		1.35		1.70		V		
Maximum reverse current @ $T_A=25^\circ\text{C}$ at rated DC blocking voltage @ $T_A=125^\circ\text{C}$	I_R	5.0 350							μA	
Typical reverse recovery time (Note1)	t_{rr}	35							ns	
Typical junction capacitance (Note2)	C_J	18							45	pF
Typical thermal resistance	$R_{\theta JA}$	50							$^\circ\text{C/W}$	
Operating junction temperature range	T_J	- 55 ---- + 150							$^\circ\text{C}$	
Storage temperature range	T_{STG}	- 55 ---- + 150							$^\circ\text{C}$	

 NOTE: 1. Measured with $I_F=0.5\text{A}$, $I_R=1\text{A}$, $I_{rr}=0.25\text{A}$.

2. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

 3. Thermal resistance from junction to ambient and junction to lead P.C.B. mounted on 0.27"X0.27"(7.0X7.0mm²) copper pad areas

FIG.1 -- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTIC



NOTES: 1. RISE TIME = 7ns MAX. INPUT IMPEDANCE = 1MΩ .22pF.
 2. RISE TIME = 10ns MAX. SOURCE IMPEDANCE = 50 Ω.

SET TIME BASE FOR 10/15 ns/cm

FIG.2 -- TYPICAL FORWARD CHARACTERISTIC

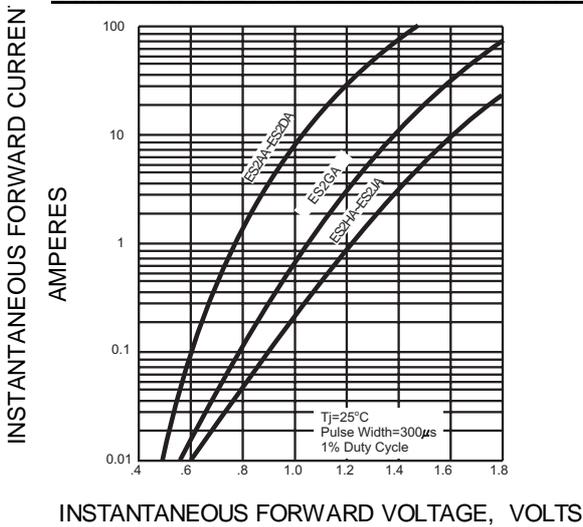


FIG.3 -- FORWARD DERATING CURVE

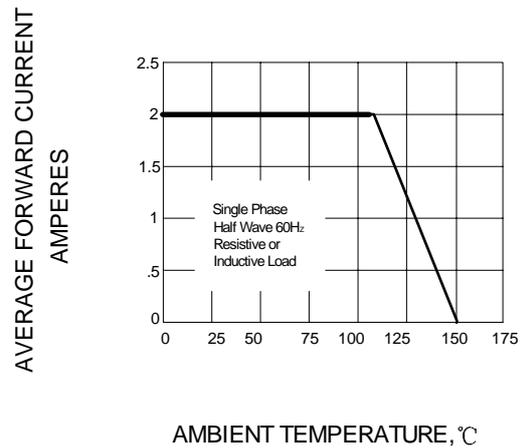


FIG.4 -- TYPICAL JUNCTION CAPACITANCE

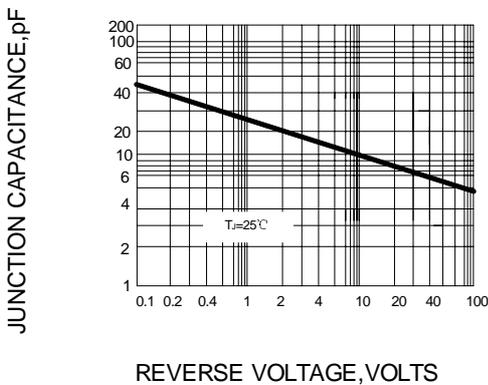


FIG.5 -- PEAK FORWARD SURGE CURRENT

